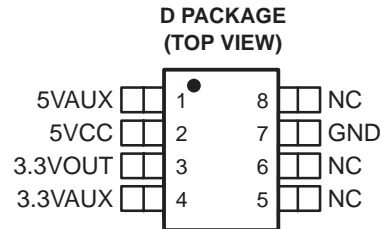


- Automatic Input Voltage Source Selection
- Glitch-Free Regulated Output
- 5-V Input Voltage Source Detector With Hysteresis
- 250-mA Load Current Capability With 5-V or 3.3-V Input Source
- Low  $r_{DS(on)}$  Auxiliary Switch



## description

The TPPM0303 is a low-dropout regulator with auxiliary power management that provides a constant 3.3-V supply at the output capable of driving a 250-mA load.

The TPPM0303 provides a regulated power output for systems that have multiple input sources and require a constant voltage source with a low-dropout voltage. This is a single output, multiple input, intelligent power source selection device with a low-dropout regulator for either 5VCC or 5VAUX inputs, and a low-resistance bypass switch for the 3.3VAUX input.

Transitions may occur from one input supply to another without generating a glitch outside of the specification range on the 3.3-V output. The device has an incorporated reverse-blocking scheme to prevent excess leakage from the input terminals in the event that the output voltage is greater than the input voltage.

The input voltage is prioritized in the following order: 5VCC, 5VAUX, and 3.3VAUX.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS  
INSTRUMENTS**

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## SLVS364 – FEBRUARY 2001

[illegible]

TERMINAL NAME	NO.	I/O	DESCRIPTION
3.3VAUX	4	I	3.3-V auxiliary input
3.3VOUT	3	O	3.3-V output with a typical capacitance load of 4.7 $\mu$ F
5VAUX	1	I	5-V auxiliary input
5VCC	2	I	5-V main input
GND	7	I	Ground
NC	5,6,8		No internal connection

**Table 1. Input Selection**

INPUT VOLTAGE STATUS (V)			INPUT SELECTED	OUTPUT (V)	OUTPUT (I)
5VCC	5VAUX	3.3VAUX	5VCC/5VAUX/3.3VAUX	3.3VOUT	I <sub>L</sub> (mA)
0	0	0	None	0	0
0	0	3.3	3.3VAUX	3.3	250
0	5	0	5VAUX	3.3	250
0	5	3.3	5VAUX	3.3	250
5	0	0	5VCC	3.3	250
5	0	3.3	5VCC	3.3	250
5	5	0	5VCC	3.3	250
5	5	3.3	5VCC	3.3	250

**absolute maximum ratings over operating free-air temperature (unless otherwise noted)†**

Supply voltage, 5-V main input, V <sub>(5VCC)</sub> (see Notes 1 and 2)	7 V
Auxiliary voltage, 5-V input, V <sub>(5VAUX)</sub> (see Notes 1 and 2)	7 V
Auxiliary voltage, 3.3-V input, V <sub>(3.3VAUX)</sub> (see Notes 1 and 2)	5 V
3.3-V output current limit, I <sub>(LIMIT)</sub>	1.5 A
Continuous power dissipation (low-K), P <sub>D</sub> (see Note 3)	0.625 W
Electrostatic discharge susceptibility, human body model, V <sub>(HBMESD)</sub>	2 kV
Operating ambient temperature range, T <sub>A</sub>	0°C to 70°C
Storage temperature range, T <sub>stg</sub>	–55°C to 150°C
Operating junction temperature range, T <sub>J</sub>	–5°C to 120°C
Lead temperature (soldering, 10 second), T <sub>(LEAD)</sub>	260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values are with respect to GND.  
2. Absolute negative voltage on these terminal should not be below –0.5 V.  
3. The device derates with increase in ambient temperature, T<sub>A</sub>. See Thermal Information section.

**recommended operating conditions**

	MIN	TYP	MAX	UNIT
5-V main input, V <sub>(5VCC)</sub>	4.5		5.5	V
5-V auxiliary input, V <sub>(5VAUX)</sub>	4.5		5.5	V
3.3-V auxiliary input, V <sub>(3.3VAUX)</sub>	3		3.6	V
Load capacitance, C <sub>L</sub>	4.23	4.7	5.17	μF
Load current, I <sub>L</sub>	0		250	mA
Ambient temperature, T <sub>A</sub>	0		70	°C

# TPPM0303

## 250-mA LOW-DROPOUT REGULATOR

### WITH AUXILIARY POWER MANAGEMENT

SLVS364 – FEBRUARY 2001

electrical characteristics over recommended operating free-air temperature range,  $T_A = 0^\circ\text{C}$  to  $70^\circ\text{C}$ ,  $C_L = 4.7\ \mu\text{F}$  (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V(5VCC)/ V(5VAUX)	5-V inputs		4.5	5	5.5	V
I(Q)	Quiescent supply current	From 5VCC or 5VAUX terminals, I <sub>L</sub> = 0 to 250 mA		2.5	5	mA
		From 3.3VAUX terminal, I <sub>L</sub> = 0 A		250	500	μA
I <sub>L</sub>	Output load current		0.25			A
I(LIMIT)	Output current limit	3.3VOUT = 0 V			2	
T(TSD) <sup>†</sup>	Thermal shutdown	3.3VOUT output shorted to 0 V	150		180	°C
T <sub>hys</sub> <sup>†</sup>	Thermal hysteresis			15		
V(3.3VOUT)	3.3-V output	I <sub>L</sub> = 250 mA	3.135	3.3	3.465	V
C <sub>L</sub>	Load capacitance	Minimal ESR to insure stability of regulated output		4.7		μF
I <sub>lkg</sub> (REV)	Reverse leakage output current	Tested for input that is grounded. 3.3VAUX, 5VAUX or 5VCC = GND, 3.3VOUT = 3.3 V			50	μA

$^\dagger$  Design targets only. Not tested in production.

#### 5-V detect

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V(TO_LO)	Threshold voltage, low	5VAUX or 5VCC ↓	3.85	4.05	4.25	V
V(TO_HI)	Threshold voltage, high	5VAUX or 5VCC ↑	4.1	4.3	4.5	V

#### auxiliary switch

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
R(SWITCH)	Auxiliary switch resistance	5VAUX = 5VCC = 0 V, 3.3VAUX = 3.3 V, I <sub>L</sub> = 150 mA			0.4	Ω
ΔV <sub>O</sub> (ΔV <sub>I</sub> )	Line regulation voltage	5VAUX or 5VCC = 4.5 V to 5.5 V		2		mV
ΔV <sub>O</sub> (ΔI <sub>O</sub> )	Load regulation voltage	20 mA < I <sub>L</sub> < 250 mA		40		mV
V <sub>I</sub> – V <sub>O</sub>	Dropout voltage	I <sub>L</sub> < 250 mA			1	V

#### thermal characteristics

PARAMETER	MIN	TYP	MAX	UNIT
$R_{\theta\text{JC}}$ Thermal impedance, junction-to-case			39	$^\circ\text{C/W}$
$R_{\theta\text{JA}}$ Thermal impedance, junction-to-ambient	Low-K (see Note 4)		176	$^\circ\text{C/W}$
	High-K (see Note 4)		98	

NOTE 4: See JEDEC PCB specifications for low-K and high-K.

## TYPICAL CHARACTERISTICS

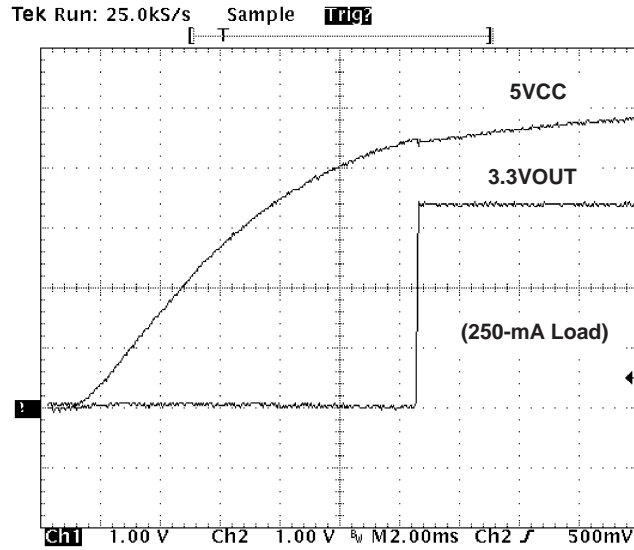


Figure 1. 5VCC Cold Start

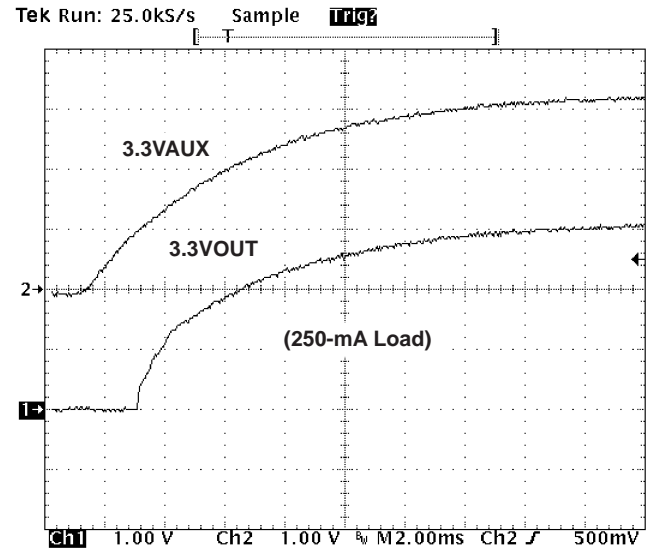


Figure 2. 3.3VAUX Cold Start

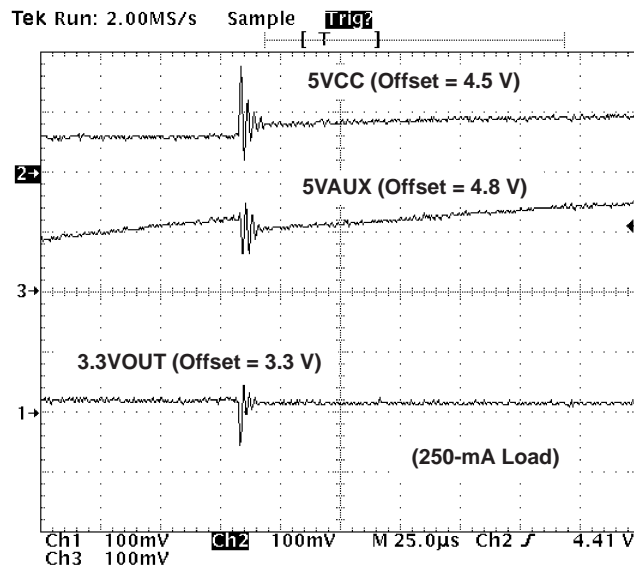


Figure 3. 5VCC Power Up (5VAUX = 5 V)

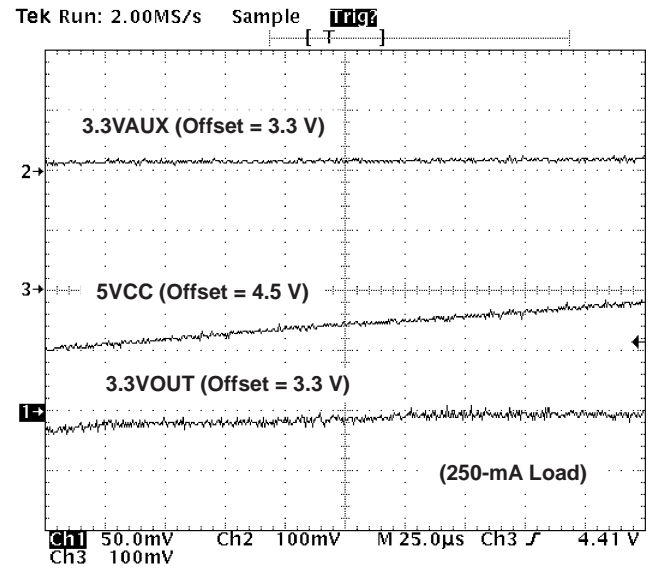


Figure 4. 5VCC Power Up (3.3VAUX = 3.3 V)

## TYPICAL CHARACTERISTICS

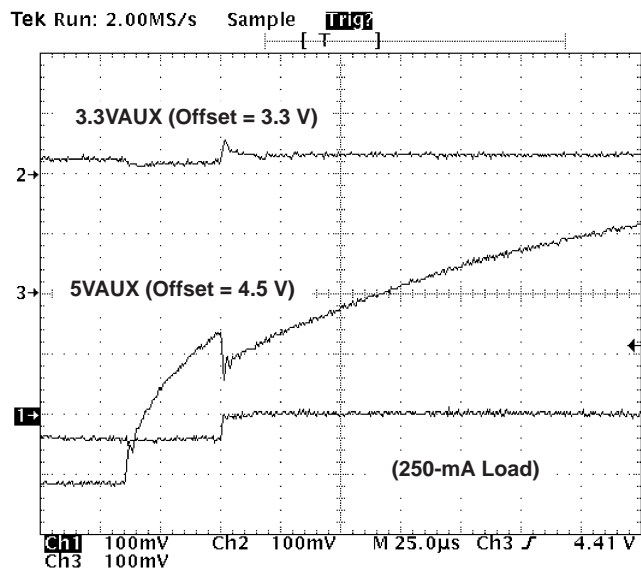


Figure 5. 5VAUX Power Up (3.3VAUX = 3.3 V)

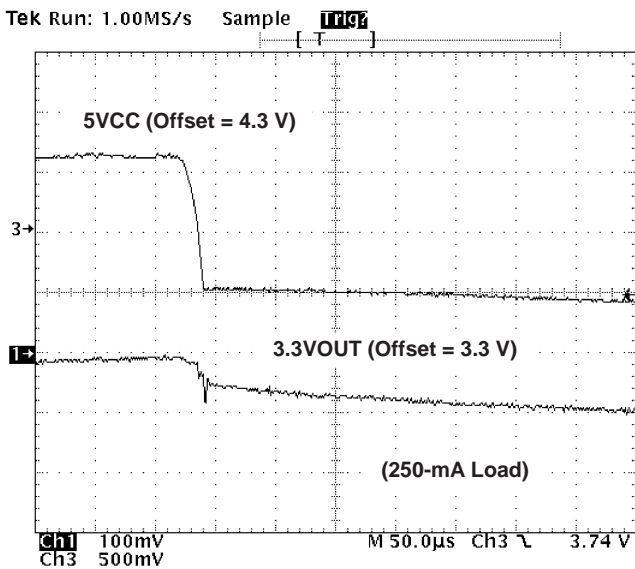


Figure 6. 5VCC Power Down (3.3VAUX = 3.3 V)

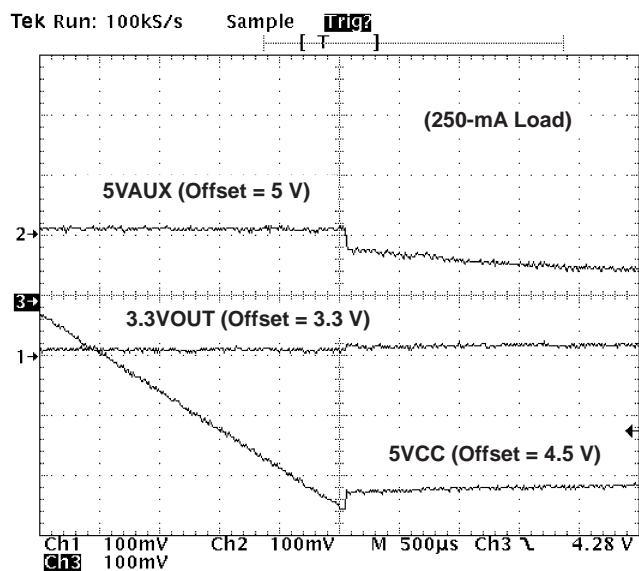


Figure 7. 5VCC Power Down (5VAUX = 5 V)

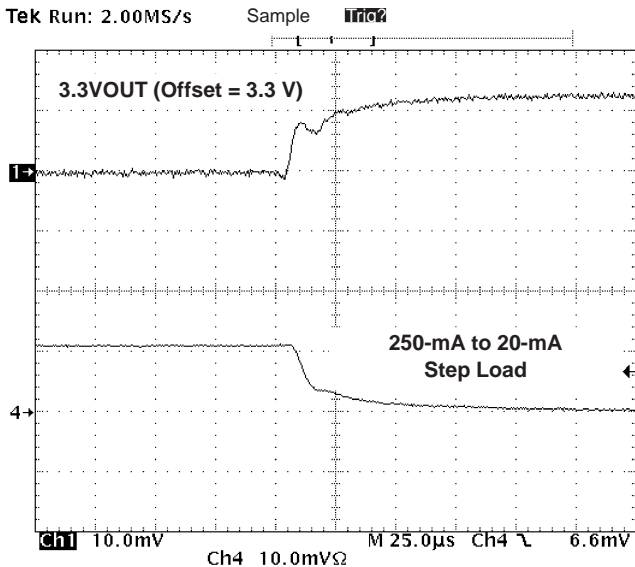
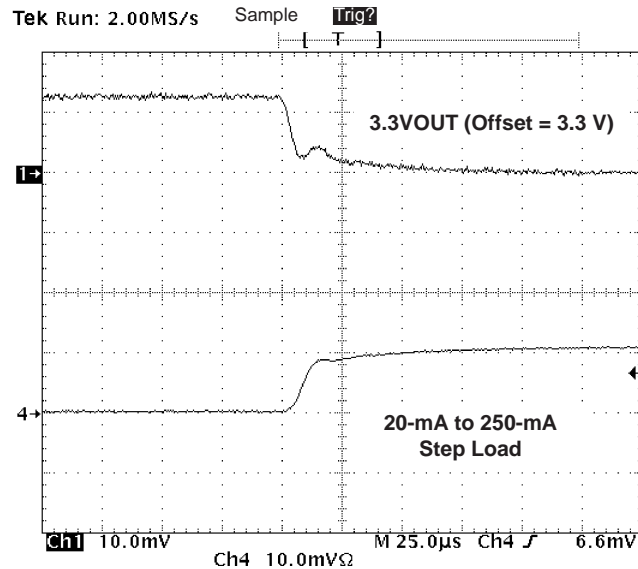


Figure 8. 5VCC Load Transient Response Falling

## TYPICAL CHARACTERISTICS



**Figure 9. 5VCC Load Transient Response Rising**

## THERMAL INFORMATION

To ensure reliable operation of the device, the junction temperature of the output device must be within the safe operating area (SOA). This is achieved by having a means to dissipate the heat generated from the junction of the output structure. There are two components that contribute to thermal resistance. They consist of two paths in series. The first is the junction to case thermal resistance,  $R_{\theta JC}$ ; the second is the case to ambient thermal resistance,  $R_{\theta CA}$ . The overall junction to ambient thermal resistance,  $R_{\theta JA}$ , is determined by:

$$R_{\theta JA} = R_{\theta JC} + R_{\theta CA}$$

The ability to efficiently dissipate the heat from the junction is a function of the package style and board layout incorporated in the application. The operating junction temperature is determined by the operating ambient temperature,  $T_A$ , and the junction power dissipation,  $P_J$ .

The junction temperature,  $T_J$ , is equal to the following thermal equation:

$$T_J = T_A + P_J (R_{\theta JC}) + P_J (R_{\theta CA})$$

$$T_J = T_A + P_J (R_{\theta JA})$$

This particular application uses the 8-pin SO package with standard lead frame with a dedicated ground terminal. Hence, the maximum power dissipation allowable for an operating ambient temperature of 70°C, and a maximum junction temperature of 150°C is determined as:

$$P_J = (T_J - T_A) / R_{\theta JA}$$

$$P_J = (150 - 70) / 176 = 0.45 \text{ W when using a low-K PCB.}$$

$$P_J = (150 - 70) / 98 = 0.81 \text{ W when using a high-K PCB.}$$

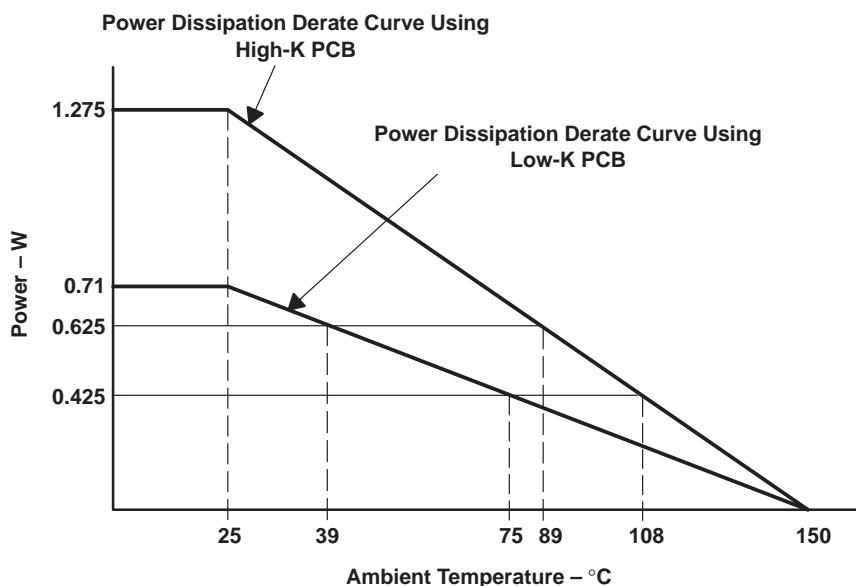
Worst case maximum power dissipation is determined by:

$$P_D = (5.5 - 3) \times 0.25 = 0.625 \text{ W}$$

Normal operating maximum power dissipation is (see Figure 10):

$$P_D = (5 - 3.3) \times 0.25 = 0.425 \text{ W}$$

## THERMAL INFORMATION



NOTE: These curves are to be used for guideline purposes only. For a particular application, a more specific thermal characterization is required.

Figure 10. Power Dissipation Derating Curves

## APPLICATION INFORMATION

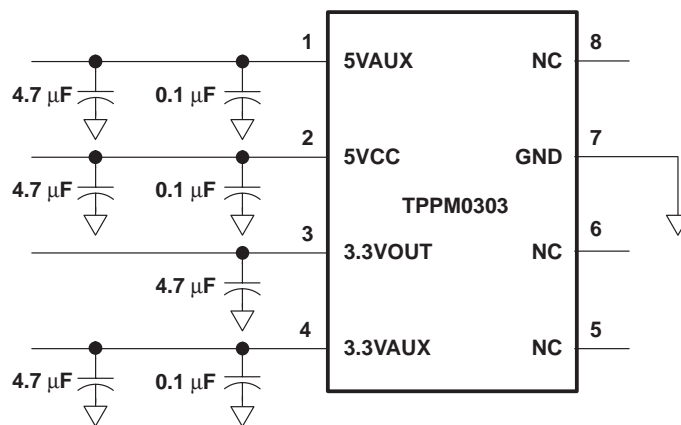


Figure 11. Typical Application Schematic

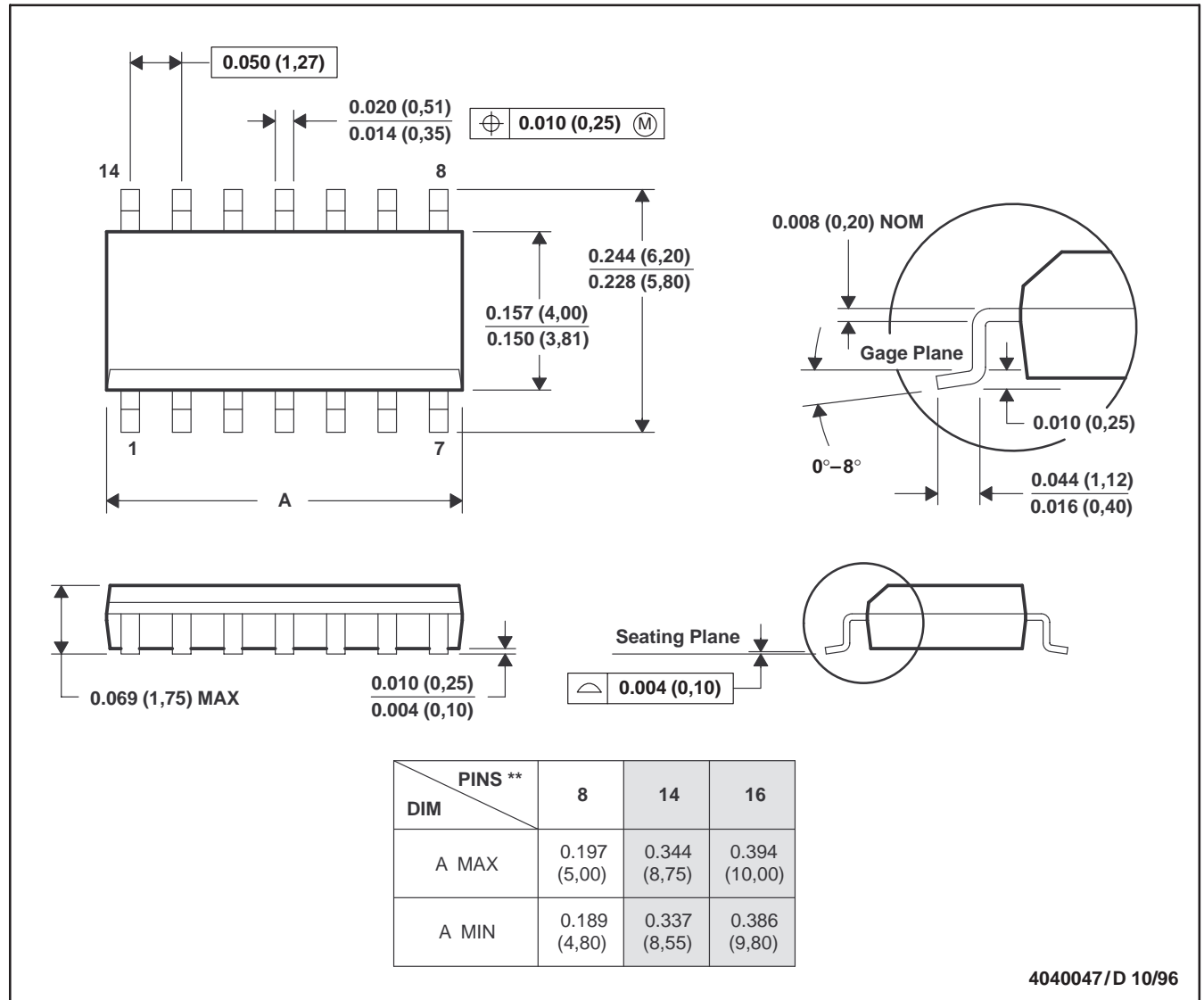


## MECHANICAL DATA

**D (R-PDSO-G\*\*)**

**PLASTIC SMALL-OUTLINE PACKAGE**

**14 PINS SHOWN**



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).  
 D. Falls within JEDEC MS-012

## PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TPPM0303D	ACTIVE	SOIC	D	8	75	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	TPPM0303	<a href="#">Samples</a>
TPPM0303DG4	ACTIVE	SOIC	D	8	75	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	TPPM0303	<a href="#">Samples</a>
TPPM0303DR	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	TPPM0303	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

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**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPPM0303DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPPM0303DR	SOIC	D	8	2500	340.5	338.1	20.6

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